

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (original): A method for manufacturing a ceramic electronic component, comprising:

 a preparation step of preparing a long composite sheet including a supporting film and a ceramic green sheet disposed on the supporting film;

 a first gravure-printing step of applying a first paste to the ceramic green sheet in a first region of the ceramic green sheet by gravure printing; and

 a second gravure-printing step of applying a second paste to the ceramic green sheet in a second region of the ceramic green sheet by gravure printing; wherein

 a first print mark is formed on the ceramic green sheet or the supporting film in the first gravure-printing step;

 the position of the first print mark formed in the first gravure-printing step is compared with a desired position of the first print mark; and

 the second gravure-printing step is performed in accordance with the result of the comparison of the position of the first print mark formed in the first gravure-printing step and the desired position of the first print mark.

Claim 2 (original): A method for manufacturing the ceramic electronic component according to Claim 1, wherein the second gravure-printing step is performed after the ceramic green sheet is moved along at least one of the width and the length thereof in accordance with the result of the comparison or while the ceramic green sheet is being moved along at least one of the width and the length thereof in accordance with the result of the comparison.

Claim 3 (original): A method for manufacturing the ceramic electronic component according to Claim 1, wherein a first imaging device and a first image-processing device are used for determining the position of the first print mark.

Claim 4 (currently amended): A method for manufacturing the ceramic electronic component according to Claim 1, wherein a second print mark is formed on the ceramic green sheet or the supporting film in the second gravure-printing step, the positions of the first and the second print marks formed in the first and the second gravure-printing steps, respectively, are compared with desired positions of the first and the second print marks, and the second gravure-printing step is repeated in accordance with the result of the comparison of the positions of the first and the second print marks formed in the first and the second gravure-printing steps and the desired positions of the first and the second print marks.

Claim 5 (currently amended): A method for manufacturing the ceramic electronic component according to Claim ~~4~~4, wherein a second print-mark-printing element provided on a plate cylinder used in the second gravure-printing step is detected for determining the position of the second print mark.

Claim 6 (original): A method for manufacturing the ceramic electronic component according to Claim 1, wherein the dimension of the first print mark extending along the length of the ceramic green sheet changes along the width of the ceramic green sheet.

Claim 7 (original): A method for manufacturing the ceramic electronic component according to Claim 4, wherein the dimension of at least one of the first print mark and the second print mark extending along the length of the ceramic green sheet changes along the width of the ceramic green sheet.

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Claim 8 (original): A method for manufacturing the ceramic electronic component according to Claim 1, wherein the first print mark has a substantially triangular shape.

Claim 9 (original): A method for manufacturing the ceramic electronic component according to Claim 4, wherein the first print mark and the second print mark have substantially triangular shapes.

Claim 10 (original): A method for manufacturing the ceramic electronic component according to Claim 1, wherein one of the first paste and the second paste is a conductive paste and the other of the first paste and the second paste is a step-reducing ceramic paste.

Claim 11 (original): A method for manufacturing the ceramic electronic component according to Claim 1, wherein the first paste and the second paste are conductive pastes.

Claims 12-21 (canceled).